



Material Content Data Sheet



Sales Product Name				IPP027N08N5		Issued		26. August 2018	
MA#				MA002805508					
Package				PG-TO220-3-1		Weight*		2036.48 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.993	0.20	0.20	1961	1961	
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		120		
	non noble metal	iron	7439-89-6	0.816	0.04		401		
	non noble metal	copper	7440-50-8	815.335	40.04	40.09	400364	400885	
	non noble metal	aluminium	7429-90-5	11.034	0.54	0.54	5418	5418	
wire	non noble metal	aluminium	7429-90-5	11.034	0.54	0.54	5418	5418	
encapsulation	organic material	carbon black	1333-86-4	8.842	0.43		4342		
	plastics	epoxy resin	-	97.262	4.78		47760		
	inorganic material	silicondioxide	60676-86-0	483.365	23.74	28.95	237353	289455	
leadfinish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10539	10539	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	120	121	
solder	non noble metal	tin	7440-31-5	0.073	0.00		36		
	noble metal	silver	7440-22-4	0.091	0.00		45		
	non noble metal	lead	7439-92-1	3.481	0.17	0.17	1710	1791	
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		87		
	non noble metal	iron	7439-89-6	0.590	0.03		290		
	non noble metal	copper	7440-50-8	589.466	28.95	28.99	289453	289830	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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